

Lextar com

VCSEL Array Module (Product Specification)

Preliminary

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Rev. A_00



Approval Sheet

PV85QD4 V5 VCSEL Array Module Product Specification



Product	VCSEL Array Module
Part Number	PV85QD4 V5
Customer	
Issue Date	2021/01/29



Features

- ✓ Compact dimensions: 3.5 mm \times 3.2 mm \times 1.6 mm
- ✓ Peak wavelength:λ p = 940 nm
- ✓ Rectangular emission pattern with a 127° x 104° diffuser
- ✓ Environmental friendly; RoHS compliance

Applications

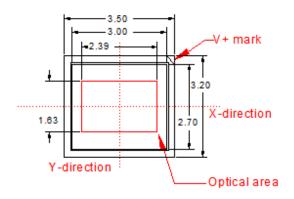
- ✓ Scene understanding with multi-object detection
- √ 3D depth assistance
- ✓ Presence detection



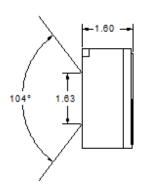
Outline Dimension

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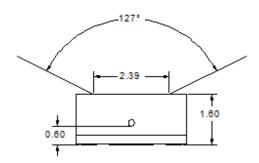
■ Package Dimension



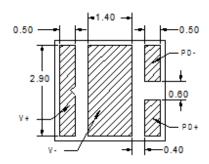
Top view



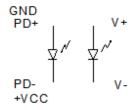
Side-Y view



Side-X view



Bottom view



Circuit Diagram

Unit: mm Tolerance: ±0.1mm



Characteristics

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■ Electro-optical Characteristics (T_a=25°C)

Parameter	Symbol	Condition	Min.	Typical	Max.	Unit
Forward Voltage	V_{F}	$I_F = 4.5 A$	1.8	2.2	2.4	V
Forward voltage temperature variation	\triangleV_F/\triangleT	$I_F = 4.5 A$		-2		mV/°C
Wavelength	λ_p	$I_F = 4.5 A$	930	940	950	nm
Wavelength temperature variation	$\Delta\lambda_p/\DeltaT$	$I_F = 4.5 A$		0.07		nm/°C
Radiant Power	Фе	$I_F = 4.5 A$	2900	3400		mW
Slope Efficiency	SE		0.6	0.8	1.1	W/A
Spectral Width(FWHM)	Δλ	$I_F = 4.5 A$	1	1.8	2.2	nm
Threshold Current	l th			0.7		А
Power Conversion	PCE	1 450	20	2.4		%
Efficiency	PCE	$I_F = 4.5 A$	30	34		70
x-direction Divergence	θ_{x}	I _F = 4.5 A		86		deg
Angle(FWHM)	O_X	IF = 4.5 A		00		ueg
y-direction Divergence	0	$I_F = 4.5 A$		78		dog
Angle(FWHM)	Θ_{y}	I _F = 4.5 A		70		deg
FOV-x	FOV_x	$I_F = 4.5 A$		127		deg
FOV-y	FOV_y	$I_F = 4.5 A$		104		deg
Series resistance	R_s	$I_F = 4.5 A$		0.18		Ohm

Note:

- (1) Lextar maintains a tolerance of ±10% on radiant power, ±0.1V on forward voltage and ±1nm on peak wavelength measurements.
- (2) All test item are measured with 0.5ms pulse current, single pulse
- (3) For divergence angle, emitted light from the package was projected on a flat screen. Divergence angle was calculated from full-width-half-maximum (FWHM) intensity distribution of the projected emission pattern.
- (4) Field of view (FOV) is distribution of radiation intensity which is measured with a goniometer system. Emitted light from package is measured by a photo-detector directly without a screen.



■ Photo-diode Electro-Optical Characteristics

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	V_{F}	$I_F = 10 \text{mA}, H = 0$	0.5		1.3	V
Reverse Breakdown Voltage	V_{BR}	$I_R = 100uA, H=0$	35			V
Reverse Dark Current	I_{D}	V _R =10V		2	10	nA
Light Current	I_{L}	$V_R=5V$ IF(VCSEL)=4.5A		2.0		mA
Peak Sensing Wavelength	λ_p			940		nm
Junction Capacitance	C_{J}	V _R =3V, H=0 F=1 MHz		2	10	рF

Absolute Maximum Ratings

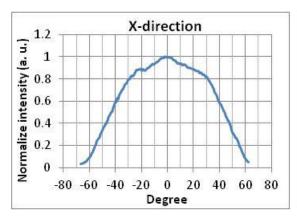
Parameter	Symbol	VALUE	Unit
Operation Temperature-extended ⁽¹⁾	T_op	-40~105	°C
Storage Temperature	T_{stg}	-40~125	°C

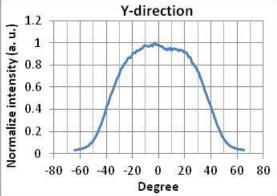
Note:

(1) Extended operation temperature for <1% of operation time



Intensity Distribution of Projected Pattern

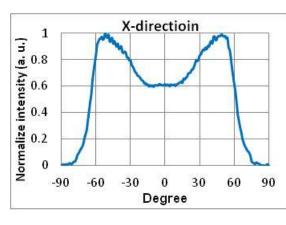


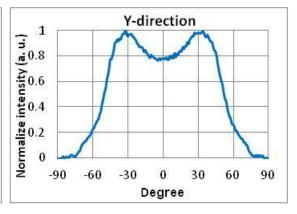


Note:

Emitted light from the package was projected on a flat screen. The projected emission pattern was captured by a CCD for obtaining intensity distribution.

Field of View



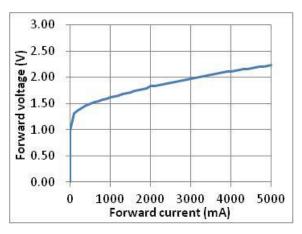


Note:

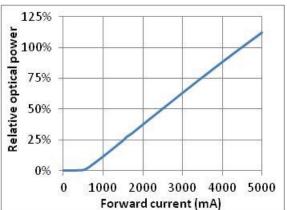
Field of view (FOV) is distribution of radiation intensity which is measured with a goniometer system. Emitted light from package is measured by a photo-detector directly without a screen.



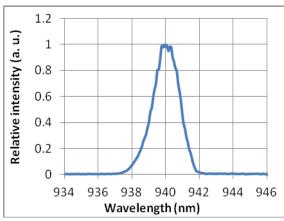
Forward Voltage vs. Current



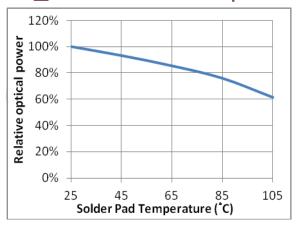
Radiant Power vs. Current



Spectrum



Radiant Power vs. Temperature

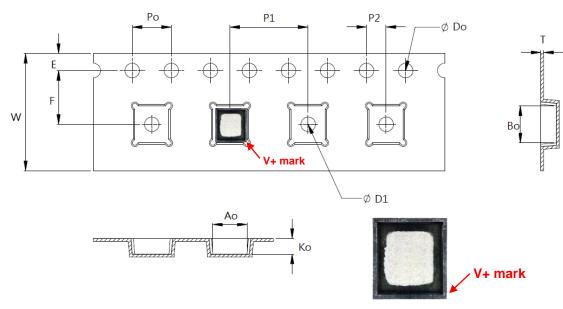




Packing

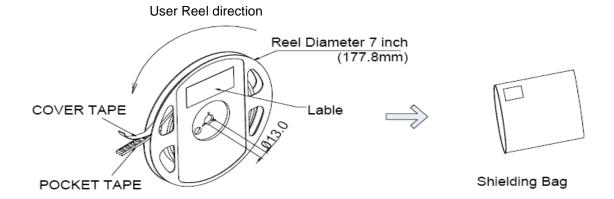
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■ Emitter Reel Packing



UNIT:mm

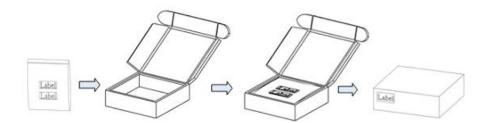
symbol	Ao	Во	Ko	Po	P1	P2	Т
spec	3.70±0.10	3.70±0.10	2.4±0.10	4.00±0.10	8.00±0.10	2.00±0.05	0.3±0.10
symbol	Е	F	Do	D1	W	10Po	
spec	1.75±0.10	5.50±0.05	1.55+0.05	1.5 min	12.0±0.30	40.0±0.20	



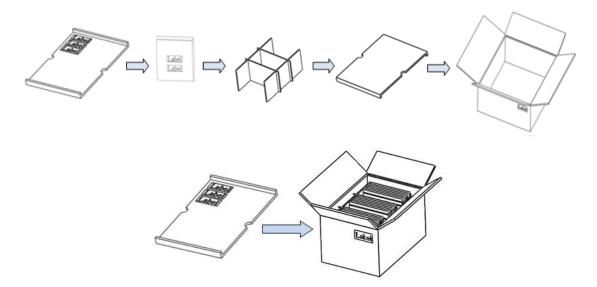
7 inch Anti-Static Reel Max 500pcs/reel Min 200pcs/reel



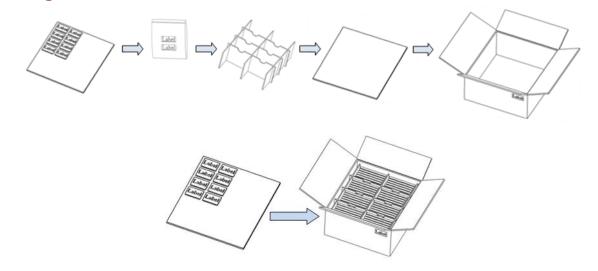
■ Small Box



■ Medium Box



■ Large Box

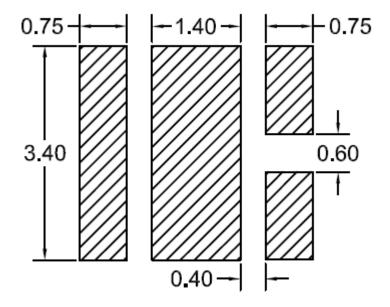




Application Notes

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■ Recommended PCB solder pads layout

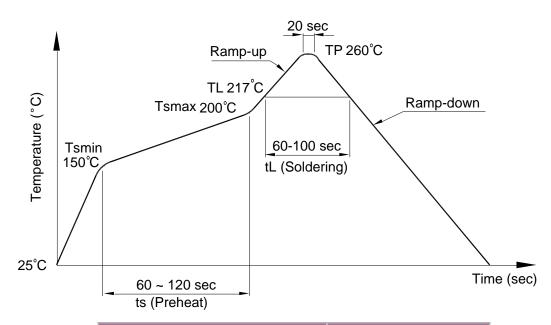


Unit: mm

Tolerance: ±0.1mm



Recommended Reflow Soldering Profile (JEDEC-STD-020 latest version compliant)



Profile Items	Conditions				
Preheat					
-Temperature Min.(T _{Smin})	150°C				
-Temperature Max.(T _{Smax})	200°C				
-Time(Min. to Max.)(t _S)	90±30 sec				
Soldering Zone					
-Temperature(T _L)	217°C				
-Time	60~100 sec				
Peak Temperature(T _P)	260°C				
Ramp-up rate	3°C / sec max.				
Ramp-down rate	3~6°C / sec				

Note:

- 1. One time soldering is recommended; do not exceed 3 times reflow process.
- 2. The recommended peak temperature is 245°C. The maximum soldering temperature should be controlled under 260°C.

Handing manual

Do not touch the lens and housing with the tweezers or fingers. Do not push on the lens. Do not apply more than 1Kg of force directly onto the lens. Excessive force on the lens could damage the PKG. Please handle the component by clamping ceramic substrate.





Storage

- Before opening the package, the Device should storage under 30℃, 70% RH.
 Recommend to use within one year.
- After opening the package bag, the Device should be keep under 30°C, 60% RH.
 Recommend to use within 7days. If unused Device remain, suggest to store into moisture proof bag or original package bag with moisture absorbent material such as silica gel.
 Reseal well is necessary.
- If the product exceeded the storage period or the moisture absorbent material faded away, baking treatment should be done by following conditions.
 Bake condition: 60℃, 12hours (One time only).

Static Electricity

- Device package is extremely sensitive to static electricity. It's recommended that
 anti-electrostatic glove and wrist ban d is necessary when handling the Device. All
 devices are also be grounded properly as well.
- Protection devices design should be considered in the Device driving circuit

Cleaning

- Do not clean the device by dipping into any liquid or flushing with any liquid.
- Recommend to clean the device by air blowing, if necessary.



Revision History

PV85QD4 V5 VCSEL Array Module Product Specification

Revision	Date	Description
A_00	29/1/2021	- Preliminary Document

单击下面可查看定价,库存,交付和生命周期等信息

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